IPC ASSOCIATION CONNICELECTRONICS INDUS	© Copyright 2005. II	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					Materials as	ials and Mfg Information				
upplier Info	ormation															
Company name*			Company unique ID			Unique ID Authority					Response Date*					
nsemi			1									2025-06-01				
Contact Name		Title - Contact			P	Phone - Contact*				Em	Email - Contact*					
Product-Env-St	tewards	Product Enviro Compliance			1	NA				Pro	Product-Env-Stewards@onsemi.com					
uthorized Rep	presentative*	Title - Representative			P	Phone - Representative*				Em	Email - Representative*					
Product-Env-St	tewards	Product Enviro Compliance			1	NA				Pro	Product-Env-Stewards@onsemi.com					
Requ	uester Item Number	er Item Number Mfr Item		n Number Mfr Item Name			Effective Date	Version	Version Manufacturing Site		Site	Weight*		UOM	Unit Type	
		NCP43080DMTTWG Secondary Side Driver for High			Synchronous Rectific Efficiency SMPS To	cation opologies	2025-06-01 MY1				8.51 mg		mg	Each		
<b>Ianufacturi</b>	ing Proccess Informat	tion														
Term	ninal Plating / Grid Array Ma	Plating / Grid Array Material To		Terminal Base Alloy J		STD-020 MSL Rating		Peak Process Body Temperat		re Max Time at Peak Tempera		perature	Numbe	r of Reflow Cyc	eles	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy		1		260		С	30		econds	conds 3			
Comments									_				_			
vel 1 - maximu	um time at peak temperatu	re during so	ldering is 10-3	0 seconds												
or more inforn	mation regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a		
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.85	mg	Supplier	Silicon (Si)	7440-21-3		0.85	mg
Die Attach Tape	0.09	mg		Epoxy resin	proprietary data		0.063	mg
			Supplier	Acrylic resins	Proprietary Data		0.027	mg
Lead Frame	2.86	mg	Supplier	Tin (Sn)	7440-31-5		0.0071	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0063	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0071	mg
			Supplier	Copper (Cu)	7440-50-8		2.8394	mg
Mold Compound-Black	4.52	mg	Supplier	Epoxy and Phenolic Resin	40216-08-8		0.3616	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0226	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.0904	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		3.9098	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.1356	mg
Plating	0.1	mg	Supplier	Palladium (Pd)	7440-05-3		0.0024	mg
			В	Nickel (Ni)	7440-02-0		0.088	mg
			Supplier	Gold (Au)	7440-57-5		0.0096	mg
Wire Bond - Au	0.09	mg	Supplier	Gold (Au)	7440-57-5		0.09	mg